Ipcsm840soldermaskpdfdownload

IPC-SM-840C January 1996

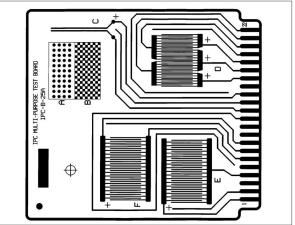


Figure 1 IPC-B-25A (Note: No solder mask is applied to contact fingers)

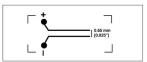


Figure 2 Test Coupon ("Y" Configuration)

Relative Degree of Cure in UV Curable Materials This method is useful in setting up and establishing control of the curing process for UV screen defined solder mask. It is not considered to be an appropriate method of determining that the proper level of solder mask cure has been achieved on actual production boards. Reasons for this include:

- The test is a measurement of depth of cure not degree of cure.
 The substrate defined in the test is a milled stainless steel block, is highly reflective and therefore allows a more complete cure than a board would see.
 The thickness of the solder mask on a real circuit

board is not always consistent, creating the potential for undercure.

IPC-TM-2.3.23.1

IPC-TM-2.3.23.1

Cure (Permanency) UV Initiated Dry Film Solder Masks This method is a nondestructive test which can be run relatively quickly. It does, however, require the use of nationative tracer materials which are in quickly evaporating solvents. Also, esperience has shown that each type of solder mask requires a different solvent for optimum reliability, it also requires knowing exactly which cure process was used to permit proper interpretation of the results. This method may have value as a process control tool, but the value as a general method for determining degree of cure is extremely limited.

6.4 Solder Mask Adhesion If a solder mask passes before soldering, and fails after soldering, the entire board system (board design, cleanliness, solder mask application, and solder mask) must be examined to determine the fail-ure mechanism.

DOWNLOAD: https://byltly.com/28r3wq



2/3

7c23cce9bc

DX-100 sounds for FM8
Proxy Switcher Pro V8.20.0.7355 Setup With Serial Key 2018 Keygenl
3 HIDDEN MODES IN ANDROID
Berapa license key fmrte 13
download cool edit for free full version

3/3